Silver/ Palladium Via Fill

GUIEML GOMEEUTTMM FRADUMTECMTMS
TC0401 is a Ag/Pd via fill (ratio Ag:Pd = 11.5:1) conductor which provides excellent compatibility with the Clad HL2000/CT800 system during the cofiring process.

The paste is recommended as a transition paste for inner vias making a connection to Au paste TC8101.

TC0401 is also compatible with Ag and Ag/Pd cofiring pastes, TC8401 and with various post firing pastes.

Key Benefits
- Transition via fill for connection with Au conductors
- Compatible with Clad HL2000/CT800
- Excellent printability
- REACH\(^1\) and ROHS\(^2\) compliant

Recommended Processing Guidelines

**Printing:**
Print through a stencil or mylar

**Drying:**
80 °C for 10 minutes

**Firing:**
See HL2000 firing profiles

**Compatibility:**
TC8101, TC8401 and Clad HL2000/CT800

**Pitch:**
≥ 1.5 mil (37.5 µm) via diameter

**Thinner:**
RV-372

**Warranty:**
Material guaranteed to meet specifications for 6 months from date of shipment.

**Storage:**
Store in a dry location at 5 – 25 °C.
DO NOT REFRIGERATE.
Allow paste to come to room temperature prior to opening. Spatulate well before using, as settling may occur during storage.

Typical Properties

**Viscosity:**
300 – 800 Kcps, Paar Physica at 10 sec\(^{-1}\), 25 °C

**Solids:**
85.0 ± 1.0 %
Legend:

1) REACH compliant according to the latest * Annex XIV to Regulation (EC) of the European Parliament and of the council on the Registration, Evaluation, Authorisation and Restriction of Chemicals ("REACH") by European Chemicals Agency and its subsequent amendments; the material does not contain any substance listed in Annex XIV.

2) RoHS compliant according to the latest * Directives (European Union) of Restriction of Hazardous Substances ("RoHS") and its subsequent amendments (including the exceptions related to Pb)